

General description

The SC14WAMDECT SF is a Cordless Audio Module with an integrated baseband, radio transceiver, power amplifier and crystal to be used in cordless microphone applications in the DECT frequency band. This module is intended for users with little or no DECT experience, who wish to make a wireless audio system.

The module can be configured for various audio applications. A *Public Address System* has two portable parts (PP) with two microphones and one fixed part (FP) configured as a receiver and integrated into a loudspeaker. Another application is a *Tour Guide System* where one a microphone (FP) broadcasts to up to 128 receivers (PP) with an integrated loudspeaker or a headset connected. The SC14WAMDECT SF module is suitable for both FP and PP usage: a hardware pin selects the function of the module.

The SC14WAMDECT SF module is pre-approved for use in all countries that use the DECT frequency band, as well as the DECT 6.0 frequency band used in North America.

Features

- Pre-programmed and ready-to-use module
- Antenna embedded, support for external antennas
- High quality audio sampled at 25.6 kHz
- Latency: 14.2 ms (PA mode), 18.3 ms (TG mode)
- UART data transfer (up to 1 kbit/s) in TG mode
- Access code for secure registration in TG mode
- ETSI (DECT) and FCC (DECT 6.0) certified
- Japan DECT (J-DECT) pre-certified
- Supports 1.9 GHz and 1.7 GHz DECT bands
- Receiver sensitivity < -93 dBm
- Transmit power EU: 23 dBm, USA: 20 dBm, JPN: 20 dBm
- Power supply voltage: 2.1 V to 3.45 V
- Supports NiMH and Alkaline batteries
- Small form factor (19.6 mm x 18.0 mm x 2.7 mm)
- Operating temperature range: -40 °C to +85 °C

Applications

- Public Address System with one or two microphones (transmitter) and one loudspeaker (receiver)
- Tour Guide System with one microphone (transmitter) and up to 128 headsets (receiver)

System diagram

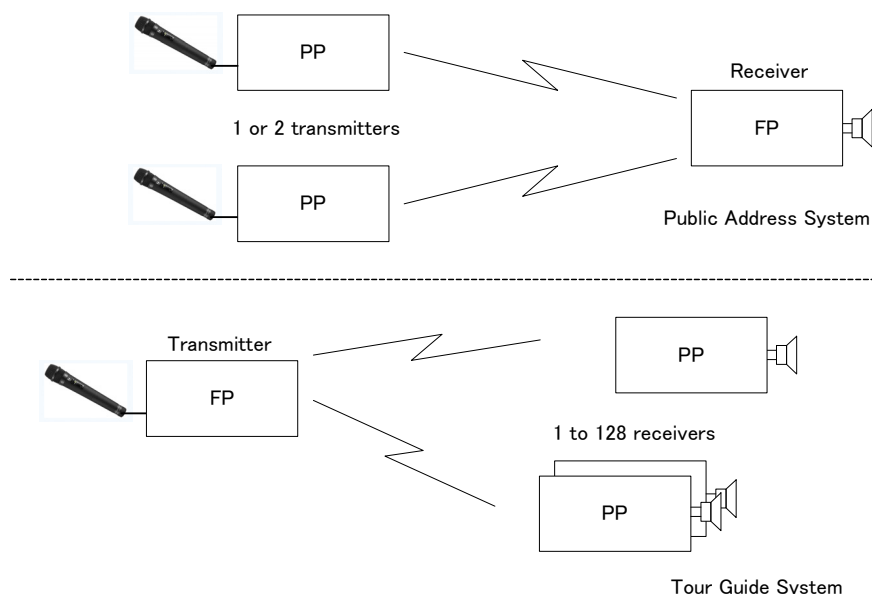


Table of Contents

1.0 Connection diagram	3	5.6.2 Internal and external antenna with FAD	15
1.1 PIN DESCRIPTION	4	6.0 Specifications	16
2.0 Introduction	7	6.1 GENERAL	16
2.1 SCOPE	7	6.2 ABSOLUTE MAXIMUM RATINGS	16
2.2 REFERENCES	7	6.3 OPERATING CONDITIONS	17
2.3 GLOSSARY AND DEFINITIONS	7	6.4 SUPPLY CURRENTS	17
3.0 Wireless Audio Module functions	8	6.5 DIGITAL INPUT/OUTPUT PINS	18
3.1 DECT	8	6.6 ANALOG FRONT END	19
3.2 MICROPHONE CONFIGURATION	8	6.7 AUDIO PERFORMANCE	21
3.3 LOUDSPEAKER CONFIGURATION	9	6.8 BASEBAND PART	22
3.4 FUNCTIONAL OVERVIEW	10	6.9 RADIO (RF) PART	23
4.0 Functional description	11	6.10 RF POWER SUPPLY	23
4.1 AUDIO CONFIGURATION	11	6.11 RF CHANNEL FREQUENCIES	24
4.1.1 Microphone connection	11	7.0 Design guidelines	25
4.1.2 Audio equalisation	11	7.1 PCB DESIGN GUIDELINES	25
4.2 POWER MANAGEMENT	11	7.2 MODULE PLACEMENT ON THE MAIN BOARD	25
4.3 OUT-OF-RANGE HANDLING	11	7.3 PATTERN FOR PIN 79 ON THE MAIN BOARD	26
4.4 PREAMBLE ANTENNA DIVERSITY	11	7.4 PRECAUTIONS REGARDING UNINTENDED	26
4.5 REGISTRATION	12	COUPLING	26
4.5.1 Handling product identities	12	8.0 Example application diagrams	27
4.5.2 Access code	12	9.0 Notices to OEM	29
4.6 DEREGISTRATION	12	9.1 FCC REQUIREMENTS REGARDING THE END	29
4.7 DATA TRANSFER	12	PRODUCT AND THE END USER	29
5.0 Usage guidelines	13	9.2 INDUSTRY CANADA REQUIREMENTS RE-	29
5.1 PUBLIC ADDRESS MODE	14	GARDING THE END PRODUCT AND THE END	29
5.1.1 Microphone (PP)	14	USER	29
5.1.2 Loudspeaker (FP)	14	9.3 END APPLICATION APPROVAL	30
5.1.3 LED indication	14	9.4 SAFETY REQUIREMENTS	30
5.1.4 Volume control	14	10.0 Package information	31
5.1.5 Accessory input/output	14	10.1 SOLDERING PROFILE	31
5.2 TOUR GUIDE MODE	14	10.2 MOISTURE SENSITIVITY LEVEL (MSL) ...	31
5.2.1 Microphone (FP)	14	10.3 COPPER PAD, SOLDER OPENING AND	32
5.2.2 Headphone (PP)	14	STENCIL	32
5.2.3 LED indication	14	10.4 MECHANICAL DIMENSIONS	34
5.2.4 Volume control	14	11.0 Revision history	35
5.2.5 Accessory input/output	15		
5.2.6 API (Tour Guide mode only)	15		
5.3 REGISTRATION	15		
5.4 DEREGISTRATION	15		
5.5 BATTERY LOW DETECTION	15		
5.6 ANTENNA OPERATION	15		
5.6.1 Internal antenna only	15		

1.0 Connection diagram

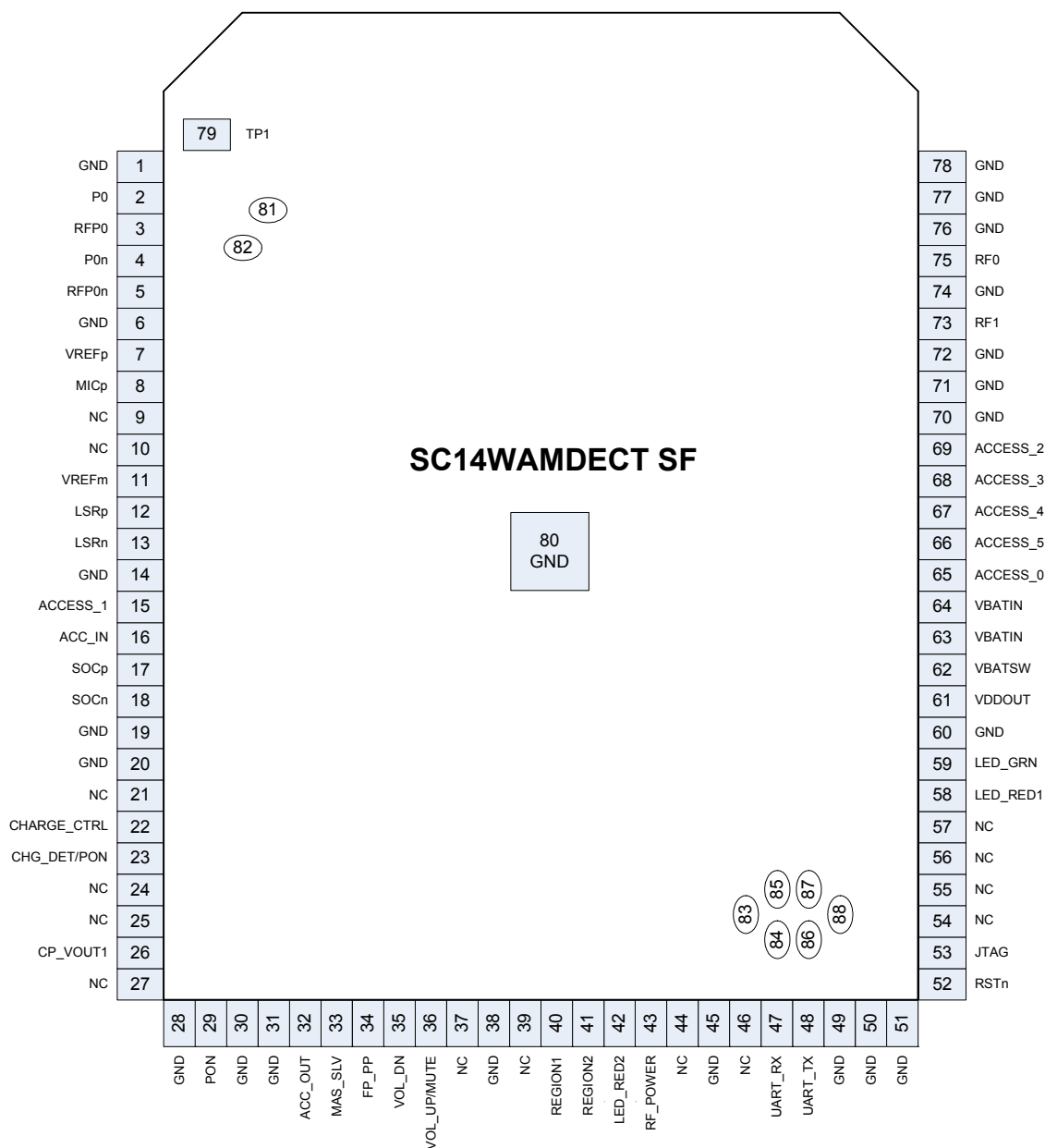


Figure 1: Connection diagram (top view, leads face down)

Table 1: Ordering information

Part number	Package	Size (mm)	Shipment form	Pack quantity
SC14WAMDECT SF01T	MOD88	18 x 19.6	Tray	60 (Note 1)

Note 1: MOQ = 600 pcs.

1.1 PIN DESCRIPTION

Table 2: Pin description

Pin	Module Pin name (Note 2)	In/Out	Iout Drive (mA)	Reset State (Note 3)	Description
1	GND	-	-	-	Ground
2	P0	O	8	Hi-Z	Control port for FAD. See section 5.6
3	RFP0	O	8	Hi-Z	Control port for FAD. See section 5.6
4	P0n	O	8	Hi-Z	Control port for FAD. See section 5.6
5	RFP0n	O	8	Hi-Z	Control port for FAD. See section 5.6
6	GND	-	-	-	Ground
7	VREFp	O	-	I	Positive microphone supply voltage.
8	MICp	I	-	I	Positive microphone input.
9	NC	-	-	-	Must be unconnected.
10	NC	-	-	-	Must be unconnected.
11	VREFm	-	-	-	Negative microphone reference (star point), connect to GND.
12	LSRp	O	-	O	Positive loudspeaker output.
13	LSRn	O	-	O	Negative loudspeaker output.
14	GND	-	-	-	Ground
15	ACCESS_1	I	-	I	TG mode: Access code bit 1. PA mode: Must be unconnected.
16	ACC_IN	I	-	I-PU	Transmitter (PA PP or TG FP): Accessory input Receiver (PA FP or TG PP): Must be unconnected.
17	SOCp	I	-	I	Battery state of charge positive input. Not used, connect to GND.
18	SOCn	I	-	I	Battery state of charge negative input. Not used, connect to GND.
19	GND	-	-	-	Ground
20	GND	-	-	-	Ground
21	NC	-	-	-	Must be unconnected.
22	CHARGE_CTRL	O	1	O-0	Charge control output. Not used, leave unconnected.
23	CHG_DET/ PON	I	-	I-PD (270k fixed pull- down)	PP: Charge Detect input. FP: Power On pushbutton input: When OFF and short press: switch ON. When ON and 2 s press: registration. When ON and 5 s press: power OFF. When ON and 10 s press: deregistration.
24	NC	-	-	-	Must be unconnected.
25	NC	-	-	-	Must be unconnected.
26	CP_VOUT1	O	-	I	Must be unconnected.
27	NC	-	-	-	Must be unconnected.
28	GND	-	-	-	Ground
29	PON	I	-	I-PD (270k fixed pull- down)	PP: Power On & Toggle Mute pushbutton input. When OFF and short press: switch ON. When OFF and 2 s press: switch ON and registration. When ON and short press: toggle mute. When ON and 2 s press: power OFF. FP: Must be unconnected.
30	GND	-	-	-	Ground
31	GND	-	-	-	Ground

Table 2: Pin description (Continued)

Pin	Module Pin name (Note 2)	In/ Out	Iout Drive (mA)	Reset State (Note 3)	Description															
32	ACC_OUT	O	8	-	Receiver (PA FP or TG PP): Accessory output Transmitter (PA PP or TG FP): Must be unconnected.															
33	MAS_SLV	I	-	I-PD	Configuration of PA and TG mode.															
34	FP_PP	I	-	I-PD	<table><tr><th>MAS_SLV</th><th>FP_PP</th><th>Mode</th></tr><tr><td>H</td><td>L</td><td>PA receiver</td></tr><tr><td>H</td><td>H</td><td>PA transmitter</td></tr><tr><td>L</td><td>L</td><td>TG transmitter</td></tr><tr><td>L</td><td>H</td><td>TG receiver</td></tr></table>	MAS_SLV	FP_PP	Mode	H	L	PA receiver	H	H	PA transmitter	L	L	TG transmitter	L	H	TG receiver
MAS_SLV	FP_PP	Mode																		
H	L	PA receiver																		
H	H	PA transmitter																		
L	L	TG transmitter																		
L	H	TG receiver																		
35	VOL_DN	I	-	I-PD	PP: Volume Down input. Connect to Volume Down pushbutton. FP: Must be unconnected.															
36	VOL_UP/ MUTE	I	-	I-PU	PP: Volume Up input. Connect to Volume Up pushbutton. FP: Mute input. When this pin is pulled LOW the FP will mute all audio to/from the PP.															
37	NC	-	-	-	Must be unconnected.															
38	GND	-	-	-	Ground															
39	NC	-	-	-	Must be unconnected.															
40	REGION1	-	-	I-PU	Selection of DECT RF frequency (FP and PP).															
41	REGION2	-	-	I-PD	<table><tr><th>REGION1</th><th>REGION2</th><th>RF BAND</th></tr><tr><td>L</td><td>L</td><td>DECT 6.0 (USA)</td></tr><tr><td>L</td><td>H</td><td>Reserved</td></tr><tr><td>H</td><td>L</td><td>Japan DECT</td></tr><tr><td>H</td><td>H</td><td>European DECT</td></tr></table>	REGION1	REGION2	RF BAND	L	L	DECT 6.0 (USA)	L	H	Reserved	H	L	Japan DECT	H	H	European DECT
REGION1	REGION2	RF BAND																		
L	L	DECT 6.0 (USA)																		
L	H	Reserved																		
H	L	Japan DECT																		
H	H	European DECT																		
42	LED_RED2	O	8	I	PA FP: Red LED 2 output (see section 5.0). Connect to VDDOUT via a series resistor (typ. 39 Ω). Other modes: Must be unconnected.															
43	RF_POWER	I	-	I-PU	RF Power mode selection input. High Power Mode (HPM): leave unconnected. Low Power Mode (LPM): connect to GND.															
44	NC	-	-	-	Must be unconnected.															
45	GND	-	-	-	Ground															
46	NC	-	-	-	Must be unconnected.															
47	UART_RX	I	-	I-PD (10k)	UART RX input, debug purposes.															
48	UART_TX	O	8	-	UART TX output, debug purposes.															
49	GND	-	-	-	Ground															
50	GND	-	-	-	Ground															
51	GND	-	-	-	Ground															
52	RSTn	I	1	I-PU (200k pull-up)	Active low Reset input with Schmitt-trigger input, open-drain output and pull-up resistor to internal VDD. Input may not exceed 2.0 V. An internal capacitor of 47 nF is mounted on this pin.															
53	JTAG	-	-	-	Debug purposes. Internally connected to VDDOUT (pin 61) via a 1 kΩ resistor.															
54	NC	-	-	-	Must be unconnected.															
55	NC	-	-	-	Must be unconnected.															
56	NC	-	-	-	Must be unconnected.															
57	NC	-	-	-	Must be unconnected.															
58	LED_RED1	O	8	I	Red LED output 1. See section 5.0 .															

Table 2: Pin description (Continued)

Pin	Module Pin name (Note 2)	In/Out	Iout Drive (mA)	Reset State (Note 3)	Description
59	LED_GRN	O	8	I	Green LED output. See section 5.0 .
60	GND	-	-	-	Ground
61	VDDOUT	-	-	-	Supply voltage output for LED_RED2 (typ. 1.8 V). Internally connected to JTAG (pin 53) via a 1 kΩ pull-up resistor.
62	VBATSW	O	8	I-PU	Supply voltage output for LED_RED1, LED_GRN (< 3.45 V).
63	VBATIN	I	-	-	Main supply voltage < 3.45 V.
64	VBATIN	I	-	-	Main supply voltage < 3.45 V.
65	ACCESS_0	I	-	I	TG mode: Access code bit 0 (LSB). PA mode: Must be unconnected.
66	ACCESS_5	I	-	I	TG mode: Access code bit 5 (MSB). PA mode: Must be unconnected.
67	ACCESS_4	I	-	I	TG mode: Access code bit 4. PA mode: Must be unconnected.
68	ACCESS_3	I	-	I	TG mode: Access code bit 3. PA mode: Must be unconnected.
69	ACCESS_2	I	-	I	TG mode: Access code bit 2. PA mode: Must be unconnected.
70	GND	-	-	-	Ground
71	GND	-	-	-	Ground
72	GND	-	-	-	Ground
73	RF1	-	-	-	RF signal for external antenna. See section 5.6
74	GND	-	-	-	Ground
75	RF0	-	-	-	RF signal for external antenna. See section 5.6
76	GND	-	-	-	Ground
77	GND	-	-	-	Ground
78	GND	-	-	-	Ground
79	TP1	-	-	-	Tuning point for internal antenna. Follow instructions of section 7.3 .
80	GND	-	-	-	Ground
81:88	TP2 to TP9	NC			Must be unconnected. See section 7.1 and Figure 13 .

Note 2: GND: internally connected to the module ground plane. Every GND pin should be connected to the main PCB ground plane.

NC: not connected.

TP: test point.

Note 3: All digital inputs have Schmitt trigger inputs. After reset all I/Os are set to input and all pull-up or pull-down resistors are enabled unless otherwise specified.

PU = Pull-up resistor enabled, PD = Pull-down resistor enabled, I = input,

O = output, Hi-Z = high impedance, 1 = logic HIGH level, 0 = logic LOW level

Refer also to Px_DIR_REGS for INPUT/OUTPUT and Pull-up/Pull-down configurations

2.0 Introduction

VES Virtual EEPROM Storage

2.1 SCOPE

WAM Wireless Audio Module

The SC14WAMDECT SF module can be configured for various audio applications. A *Public Address System* has two portable parts (PP) each with a microphone and one fixed part (FP) configured as a receiver and integrated into a loudspeaker. Another application is a *Tour Guide System*, where one microphone is the FP which broadcasts to up to 128 (PP) receivers with an integrated loudspeaker or with a headset connected.

2.2 REFERENCES

1. AN-D-218, SC14WAMDECT External antenna design guidelines, Application note, Dialog Semiconductor.
2. AN-D-223, SC14WAMDECT production pairing, Application Note, Dialog Semiconductor.
3. FpApiProject.pdf, Specification for interface between FpApiProject and Host in WAM project, Dialog Semiconductor.
4. PpApiProject.pdf, Specification for interface between PpApiProject and Host in WAM project, Dialog Semiconductor.

2.3 GLOSSARY AND DEFINITIONS

DECT	Digital Enhanced Cordless Telephone
ESD	Electro Static Discharge
FAD	Fast Antenna Diversity
FP	Fixed Part; the microphone for the TG system or the speaker for the PA system.
GFSK	Gaussian Frequency Shift Keying
HW	Hardware
IPEI	International Portable Equipment Identity (refer to ETSI EN 300 175-6)
MMI	Man Machine Interface
NC	Not Connected
PA	Public Address (System)
PCB	Printed Circuit Board (without components)
PP	Portable Part; the microphone for the PA system or the speaker for the TG system.
RF	Radio Frequency
RFPI	Radio Fixed Part Identity (refer to ETSI EN 300 175-6)
RSSI	Radio Signal Strength Indication (please refer to ETSI EN 300 175-1)
SOC	State Of Charge
SW	Software
TG	Tour Guide (System)

3.0 Wireless Audio Module functions

This section describes the key functions and features supported by the SC14WAMDECT SF module.

3.1 DECT

The SC14WAMDECT SF is based on the ETSI DECT specifications for digital cordless telephone systems.

The system diagram on [page 1](#) shows that this module has two configurations: microphone (MIC) and loud-speaker (SPEAKER).

One internal antenna is embedded and an external antenna is supported (see [section 5.6](#)). An external microcontroller can be used for limited control purposes via the UART interface. See [section 4.7](#).

3.2 MICROPHONE CONFIGURATION

For a microphone configuration the SC14WAMDECT SF module requires the external parts listed in [Table 3](#).

Table 3: Microphone configuration overview

Item	Supported	Remark
Battery	Yes	2 NiMH or standard Alkaline cells. Note: For Lilon batteries an external LDO is required.
Microphone	Yes	Connect to pin MICp (single ended).
Keys	Yes	Connect to pins ACC_IN, PON, VOL_UP/MUTE and VOL_DN.
LEDs	Yes	Connect to pins LED_RED1 and LED_GRN.

[Figure 2](#) shows the usage of the module with an external microphone. This MIC configuration can be used for the PP of a Public Address System and for the FP of a Tour Guide System.

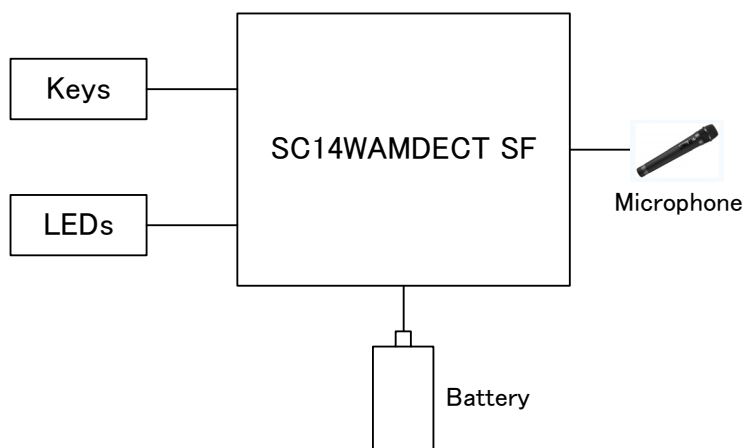


Figure 2: MIC configuration

3.3 LOUDSPEAKER CONFIGURATION

For a loudspeaker configuration the SC14WAMDECT SF module requires the external components listed in [Table 4](#).

Table 4: Loudspeaker configuration overview

Item	Supported	Remark
Battery	Yes	2 NiMH or standard Alkaline cells.
Loudspeaker	Yes	Connect to pins LSRp and LSRn (differential).
Keys	Yes	Connect to pins CHG_DET/PON, VOL_UP/MUTE and VOL_DN.
LEDs	Yes	PA mode: Connect to pins LED_RED1, LED_RED2 and LED_GRN. TG mode: Connect to pins LED_RED1 and LED_GRN.

[Figure 3](#) shows the use of the module in a typical loudspeaker configuration. This SPEAKER configuration can be used for the FP of a Public Address System and for the PP of a Tour Guide System.

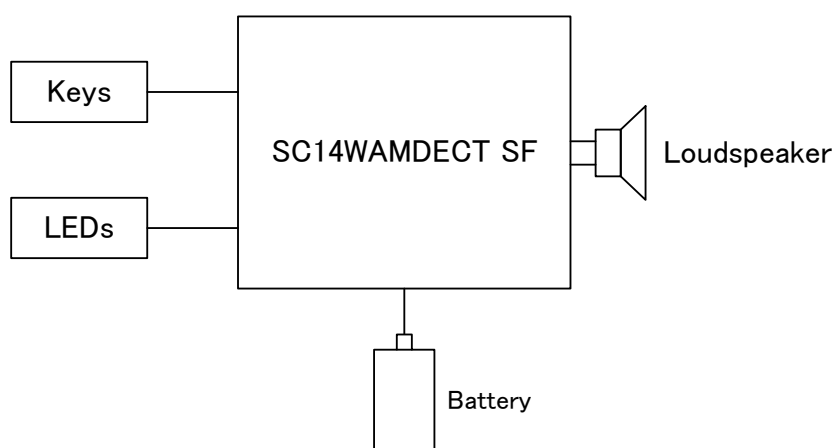


Figure 3: SPEAKER configuration

3.4 FUNCTIONAL OVERVIEW

Table 5: Overview of supported functions

Functionality	Remark
Connection handling	
PP to FP	PA mode: 1 or 2 microphones (PP) transmit to one loudspeaker (FP).
FP to PP	TG mode: 1 microphone (FP) broadcasts to max. 128 loudspeakers (PP).
Protocol	
Registration	Manual. TG mode: optionally protected by 6-bit access code.
Number of PPs per FP	PA mode: 1 or 2 TG mode: 1 to 128
Link establishment time	2 s (typ.)
Registration time-out	FP: 600 s (TG mode) PP: 120 s (TG mode)
Factory registration	Wire registration is supported. See [2].
Audio and tone	
Microphone mute	Mute of MIC in all audio connections is possible.
Latency	PA mode: 1 MIC: 14.2 ms, 2 MICs: 14.2 ms or 15.8 ms (Note 4). TG mode: 18.3 ms (Note 5).
General	
Battery handling	Charging is not supported, requires external components.

Note 4: Latency for 2 microphones depends on the assigned slot.

Note 5: For Tour Guide System the 'normal delay' applies as defined in the DECT specification.

4.0 Functional description

4.1 AUDIO CONFIGURATION

The SC14WAMDECT SF module supports a dedicated audio channel. The gains can be adjusted to meet the audio level requirements by using the SC14WAMDECT SF application reference design. For other acoustic designs it is needed to adjust and tune the audio setup.

4.1.1 Microphone connection

The SC14WAMDECT SF module only supports single-ended connection of a microphone.

4.1.2 Audio equalisation

To enable adjustments of the frequency response the SC14WAMDECT SF contains two programmable filters in the TX direction (see Figure 4).

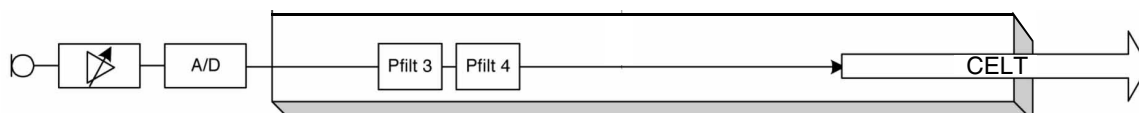


Figure 4: MIC audio routing

4.2 POWER MANAGEMENT

To minimise the current consumption the SC14WAMDECT SF module will shut down all codec amplifiers in Idle state. This means that all reference voltages in the front-end will be disabled.

4.3 OUT-OF-RANGE HANDLING

When the PP goes in-range or out-of-range a signal is sent from the PP to the MMI software indicating whether the PP is in-lock or is out-of-lock with the FP. This is used to indicate the link status via pins LED_RED1 and LED_RED2 on the FP.

4.4 PREAMBLE ANTENNA DIVERSITY

To optimise the audio quality during rapidly changing radio paths (fading), the SC14WAMDECT SF supports preamble antenna diversity. The preamble diversity algorithm uses RSSI measurements to judge the radio signal strength on both antennas and determine the best performing antenna. This antenna will be used for the receive slot and for the next transmit slot.

The software embedded in the SC14WAMDECT SF supports antenna diversity for both FP and PP with at least one external antenna. Refer to [section 5.6](#) and [1] for more detailed information.

4.5 REGISTRATION

The PP and the FP must be paired using a procedure called Registration. Without registration the PP will be out-of-lock and unable to establish a link to a FP. Therefore it will not be able to make a call.

The registration uses the unique product identities and secures the PP and FP to allow no cross-communication. To avoid cross-communication it is very important that all the PPs and the FP use a unique numbering scheme, which is standard in DECT based systems.

It is possible to pair a PP and FP during production using the production interface including wire registration. See [2].

4.5.1 Handling product identities

To ensure that the FP and PPs do not make cross-communications a unique ID must be entered into the VES of the FP and PP. For DECT products, the FP identifier is called the RFPI and the PP identifier is called the IPEI. These numbers are factory settings.

After a successful registration, the IPEI is stored in the FP and the RFPI is stored in the PP. In this way the two parts are known to each other and are allowed to make connections. See [Figure 5](#).

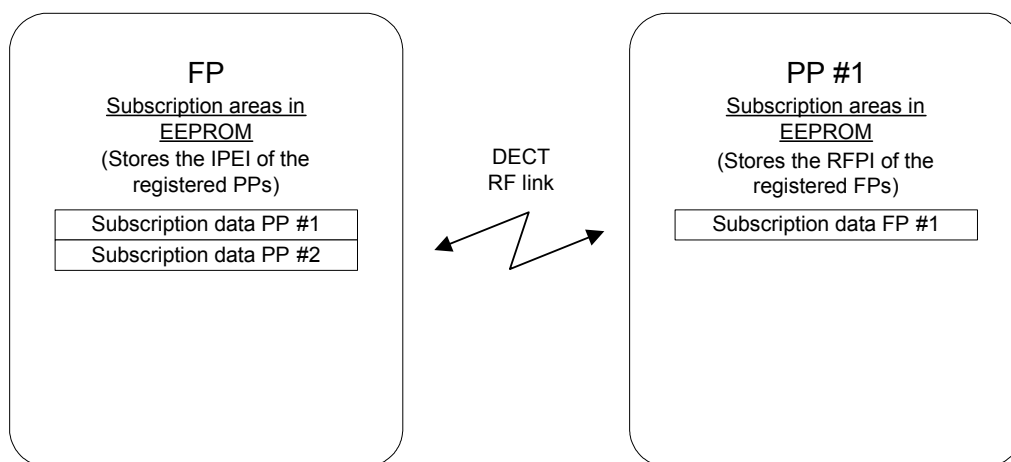


Figure 5: Handling product identities

4.5.2 Access code

In TG mode a 6-bit access code (0x00 to 0x3F) can be defined via pins ACCESS_0 to ACCESS_5. The bit pattern on the ACCESS_x pins of the FP must be set before registration and needs to remain stable during registration. For successful registration of a PP the access codes of PP and FP must be the same.

4.6 DEREGISTRATION

There are two ways of deregistering a PP from an FP:

- **PP registration:**
After successful PP registration an existing FP pairing will be overwritten. This method can be used when the PP should be combined with another FP and the original registration should be removed.
- **FP deregistration:**
During FP deregistration all existing PP pairings are removed. This method can be used when the original PPs were lost.

4.7 DATA TRANSFER

In Tour Guide mode an API function is available for broadcasting data from FP to PP via the UART at a rate of 1 kbit/s. The data is transmitted in packets of maximum 20 bytes. No data interpretation is done.

For more information on this API function, see [3] and [4]. A software example ("Sendmail") of data transfer via UART is available on request.

5.0 Usage guidelines

This section outlines the usage guidelines for both applications: **Public Address mode** (PA system) and **Tour Guide mode** (broadcasting).

Initially the Public Address mode is described. Many of the user functions and behaviours in the Tour Guide mode are the same and therefore are not repeated in the Tour Guide section.

Note: The end product user must not be able to switch between the two modes. Only when designing and manufacturing the end product shall the operating mode be assigned.

5.1 PUBLIC ADDRESS MODE

In Public Address mode one or two battery operated wireless microphones (PP, transmitter) connect to a standalone loudspeaker (FP, receiver).

5.1.1 Microphone (PP)

The wireless microphone can be a standard handheld microphone or a belt pack with a lavalier microphone attached. The SC14WAMDECT SF module (transmitter, PP) can be integrated into the microphone.

The microphone or belt pack should have three LEDs (two red and one green), a Power On button and two optional pushbuttons for volume up and down.

5.1.2 Loudspeaker (FP)

The SC14WAMDECT SF module (receiver, FP) can be integrated directly into a loudspeaker or an amplifier. In the use case described below it is assumed that the module is built into a simple loudspeaker with integrated amplifier.

The loudspeaker can be mains or battery operated. The loudspeaker should have three status LEDs (two red and one green) and one pushbutton, which acts as both Power On and Registration button.

The Power On button will normally be connected to the power switch of the loudspeaker/amplifier. The Registration button is used for pairing of a wireless microphone with the loudspeaker.

5.1.3 LED indication

A green LED and two red LEDs indicate the status of the module. The indications apply for both FP and PP. Pins LED_RED1 and LED_RED2 indicate the status of microphones 1 and 2. See [Table 6](#).

Table 6: LED status indications

LED_GRN	LED_REDx	Description
OFF	OFF	module OFF
ON	OFF	module ON, no link
OFF	ON	module ON, link good
OFF	flash 0.5 s	mute (MIC or SPEAKER)
OFF	flash 1 s	registration ongoing
flash 0.25 s	OFF	battery LOW, link good
flash 0.5 s	OFF	battery LOW, no link

5.1.4 Volume control

The microphone can have optional Volume Up and Volume Down keys. The volume control range is:

- Microphone volume: 0 dB to +30 dB, 2 dB/step, default value: +10 dB.
- Loudspeaker volume: fixed at 0 dB.

To mute the microphone press and release the Power On button (toggle).

To mute both microphones from the loudspeaker side (FP), press and hold the Volume Up key. The audio will be muted as long as this key is pressed.

5.1.5 Accessory input/output

The accessory input (pin ACC_IN) for the microphone (PP) and the accessory output (pin ACC_OUT) for the loudspeaker (FP) are supported as shown in [Table 7](#).

Table 7: Accessory I/O function table (PA mode)

ACC_IN (PP1)	ACC_IN (PP2)	ACC_OUT (FP)
L	L	H
L	H	L
H	L	L
H	H	L

Pin ACC_OUT could be used to control an external audio amplifier to drive large loudspeakers.

5.2 TOUR GUIDE MODE

In Tour Guide mode a microphone (FP, transmitter) broadcasts to up to 128 headphones (PP, receiver). After pairing to the FP, all headphones will receive the same audio signal from the microphone.

5.2.1 Microphone (FP)

The microphone is the audio transmitter and should include two LEDs (red and green), a Power On button and two optional pushbuttons for volume up and down. The SC14WAMDECT SF module (transmitter, FP) can be integrated into the microphone.

5.2.2 Headphone (PP)

The SC14WAMDECT SF module (receiver, PP) is normally built into the headphone and directly connected to the loudspeaker.

5.2.3 LED indication

A green and a red LED (pin LED_RED1) indicate the status of the module. The indications apply for both FP and PP. Pin LED_RED2 is not used. See [Table 6](#).

5.2.4 Volume control

The headphone can have optional Volume Up and Down pushbuttons. The volume control range is:

- Microphone volume: fixed at +10 dB.
- Loudspeaker volume: -12 dB to +2 dB, 2 dB/step, default value: +2 dB.

To mute the loudspeaker (receiver) press and release the Power On button (toggle). To mute the microphone (transmitter) press and hold the Volume Up key. The audio will be muted as long as this key is pressed.

5.2.5 Accessory input/output

The accessory input (pin ACC_IN) for the microphone (FP) and the accessory output (pin ACC_OUT) for the loudspeaker (PP) are supported as shown in Table 8.

Table 8: Accessory I/O function table (TG mode)

ACC_IN (FP)	ACC_OUT (PP)
L	H
H	L

5.2.6 API (Tour Guide mode only)

The SC14WAMDECT SF software has a simple API to control the module from an external host processor. The API supports the following basic functions for Tour Guide mode operation:

- Registration on/off
- Set/get access code
- Mute/unmute audio
- Get status (Registration mode/Audio/Mute/Low battery)
- Data transfer up to 1 kbit/s from FP to PP

5.3 REGISTRATION

The procedure for FP-to-PP pairing is the same for Public Address mode and Tour Guide mode:

1. Turn off PP and turn on FP.
2. Set 6-bit access code via pins ACCESS_0 to ACCESS_5. Do not change during registration.
3. FP: Press and hold PON button (pin 23) for 2 s, until the red LED1 starts flashing.
4. PP: Press and hold PON button (pin 29) for 2 s, until red LED1 starts flashing.
5. When flashing stops and the red LEDs are continuously on, registration has succeeded.

5.4 DEREGISTRATION

The procedure for FP-to-PP unpairing is the same for Public Address mode and Tour Guide mode:

1. Turn off PP.
2. FP: Press and hold PON button (pin 23) for 10 s.
3. The red LED1 will flash 3 times (0.5 s interval) and all registrations will be cleared.

5.5 BATTERY LOW DETECTION

The SC14WAMDECT SF includes a battery low detection circuit. A battery low condition is indicated by a flashing green LED.

- Battery low voltage: 2.3 V (default)

5.6 ANTENNA OPERATION

Figure 6 shows the internal circuit of the SC14WAMDECT SF.

Pin RF0 is used for two external antennas and can also be used for RF test purposes. Therefore it is recommended to add a reserve pattern for a 10 pF capacitor, even when the two external antennas are not used.

Re-certification of the SC14WAMDECT SF is required when at least one external antenna is added. On request, Dialog Semiconductor can provide a pre-certified PCB layout for an external antenna circuit.

Pin RF1 is recommended for connecting an RF cable to perform conducted tests for type approval.

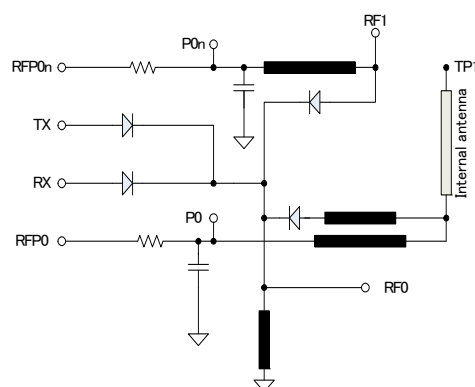


Figure 6: Internal circuit of the SC14WAMDECT SF

5.6.1 Internal antenna only

When only the internal antenna is used, the FAD function is disabled. In this case pins RFP0, RFP0n, P0 and P0n must be left unconnected.

5.6.2 Internal and external antenna with FAD

Figure 7 shows one external antenna connected to pin RF1 of the SC14WAMDECT SF. This configuration supports the FAD function. In this case pins RFP0, RFP0n, P0 and P0n must be left unconnected. See [1] for more detailed information.

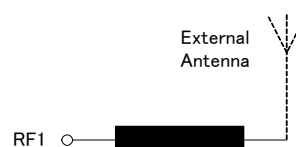


Figure 7: One external antenna

6.0 Specifications

All MIN/MAX specification limits are guaranteed by design, or production test, or statistical methods unless note 6 is added to the parameter description. Typical values are informative.

Note 6: This parameter will not be tested in production. The MIN/MAX values are guaranteed by design and verified by characterisation.

6.1 GENERAL

Table 9: SC14WAMDECT SF module

ITEM	CONDITIONS	VALUE	UNIT
Dimensions	l x w x h	18.0 x 19.6 x 2.7	mm
Weight		1.5	g
Temperature range		-40 to +85	°C
Frequency range	According to DECT standard	1870 to 1930	MHz
Antenna range	According to DECT standard; (Note 7)		
	- typical outdoor	350	m
	- typical indoor	75	m
Standards compliancy	ETS 300 444 (DECT GAP), former TBR2214 FCC part 15		
Power supply	2 cells (NiMH / Alkaline)	2.10 to 3.45	V
Maximum PCB warpage	For entire reflow range	0.1	mm

Note 7: The resulting range is very dependent on the mechanical design. Dialog Semiconductor is not responsible for this design and as such Dialog Semiconductor is not responsible for the resulting performance range of the final product.

6.2 ABSOLUTE MAXIMUM RATINGS

Table 10: Absolute Maximum Ratings (Note 8)

PARAMETER	DESCRIPTION	CONDITIONS	MIN	MAX	UNIT
Vbat_max	Max voltage on pin VBATIN			3.45	V
Vpon_max	Max voltage on pin PON			5.5	V
Vled_max	Max voltage on pin Grn LED, Red LED1			3.6	V
Vdig_bp_max	Max voltage on digital pins with back drive protection; UART_RX			3.6	V
Vdig_max	Max voltage on other digital pins			2.0	V
Vana_max	Max voltage on analog pins			2.2	V
Vesd_hbm	ESD voltage according to human body model; all pins			2000	V
Vesd_mm	ESD voltage according to machine model; all pins			150	V

Note 8: Absolute maximum ratings are those values that may be applied for maximum 50 h. Beyond these values, damage to the device may occur.

6.3 OPERATING CONDITIONS

Table 11: Operating Conditions (Note 9)

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
Vbat	Supply voltage on pin VBATIN		2.1		3.45	V
Vpon	Voltage on pin PON				5.5	V
Vdig_bp	Voltage on digital pins with back drive protection; UART_RX				3.45	V
Vdig	Voltage on other digital pins	VDD = 1.8 V			1.98	V
Vana	Voltage on analog pins	VDD = 1.8 V			2.1	V
Icharge	Current through pin CHG_DET	Rseries > (Vcharge-3 V)/10 mA			10	mA
Iout_vrefp	Output current through pin VREFp				1	mA
TA	Ambient temperature	(Note 10)	-40		+85	°C

Note 9: Within the specified limits, a life time of 10 years is guaranteed.

Note 10: Within this temperature range full operation is guaranteed.

6.4 SUPPLY CURRENTS

The supply currents in Table 12 and Table 13 have been measured using a DC voltmeter across a 0.22 Ω series resistor between the positive battery terminal and pin VBATIN.

Table 12: Supply currents: Public Address mode

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
Ibat_PA_stby	Standby supply current (PA mode)	FP (RX); LPM; Vbat = 2.6 V		95		mA
		FP (RX); HPM; Vbat = 2.6 V		114		mA
		FP (RX); HPM/U; Vbat = 2.6 V		96		mA
		PP (TX); Vbat = 2.6 V		45		mA
Ibat_PA_talk	Talk mode supply current (PA mode)	FP (RX); LPM; 1 PP (TX); Vbat = 2.6 V		132		mA
		FP (RX); HPM; 1 PP (TX); Vbat = 2.6 V		151		mA
		FP (RX); HPM/U; 1 PP (TX); Vbat = 2.6 V		134		mA
		FP (RX); LPM; 2 PPs (TX); Vbat = 2.6 V		155		mA
		FP (RX); HPM; 2 PPs (TX); Vbat = 2.6 V		191		mA
		FP (RX); HPM/U; 2 PPs (TX); Vbat = 2.6 V		168		mA
		PP (TX); LPM; Vbat = 2.6 V		120		mA
		PP (TX); HPM; Vbat = 2.6 V		174		mA
		PP (TX); HPM/U; Vbat = 2.6 V		143		mA

Table 13: Supply currents: Tour Guide mode

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
I _{bat_TG_stby}	Standby supply current (TG mode)	FP (TX); LPM; V _{bat} = 2.6 V		102		mA
		FP (TX); HPM; V _{bat} = 2.6 V		125		mA
		FP (TX); HPM/U; V _{bat} = 2.6 V		106		mA
		PP (RX); V _{bat} = 2.6 V		45		mA
I _{bat_TG_talk}	Talk mode supply current (TG mode)	FP (TX); LPM; V _{bat} = 2.6 V		137		mA
		FP (TX); HPM; V _{bat} = 2.6 V		200		mA
		FP (TX); HPM/U; V _{bat} = 2.6 V		159		mA
		PP (RX); LPM; V _{bat} = 2.6 V		85		mA
		PP (RX); HPM; V _{bat} = 2.6 V		94		mA
		PP (RX); HPM/U; V _{bat} = 2.6 V		90		mA

6.5 DIGITAL INPUT/OUTPUT PINS

Table 14: Digital input levels

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
V _{il_dig}	Logic 0 input level; all digital input pins except PON, CHG_DET and RSTn	VDD = 1.8 V			0.3*VDD	V
V _{il_pon}	Logic 0 input level; pin PON				0.9	V
V _{il_charge}	Logic 0 input level; pin CHG_DET				0.9	V
V _{il_rst}	Logic 0 input level; pin RSTn	VDD = 1.8 V			0.2*VDD	V
V _{ih_dig}	Logic 1 input level; all digital input pins except PON, CHG_DET and RSTn	VDD = 1.8 V	0.7*VDD			V
V _{ih_pon}	Logic 1 input level; pin PON		1.5			V
V _{ih_charge}	Logic 1 input level; pin CHG_DET		1.5			V
V _{ih_rst}	Logic 1 input level; pin RSTn	VDD = 1.8 V	0.8*VDD			V

Table 15: Digital output levels

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
V _{ol_dig}	Logic 0 output level	VDD = 1.8 V; I _{out} = 2, 4, 8 mA (Note 11)			0.2*VDD	V
V _{oh_dig}	Logic 1 output level	VDD = 1.8 V; I _{out} = 2, 4, 8 mA (Note 11)	0.8*VDD			V

Note 11: For output drive capability, see section "Pin Description" on page 4.

6.6 ANALOG FRONT END

Table 16: Microphone amplifier

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
Vmic_0dB_unt	Untrimmed differential RMS input voltage between MICp and MICn (0 dBm0 reference level) (Note 6)	0 dBm0 on COUT (Note 13) MIC_GAIN[3:0] = 0, @ 1020 Hz; Tolerance: • 13% when untrimmed (BANDGAP_REG=8) (Note 12) • 6% when trimmed (Note 14)	114	131	149	mV
Rin_mic	Resistance of activated microphone amplifier inputs (MICp, MICn and MICn) to internal GND (Note 6)		75	150		kΩ
Vmic_offset	Input referred DC-off-set (Note 6)	MIC_GAIN[3..0] = 1111 3 sigma deviation limits	-2.6		+2.6	mV

Note 12: BANDGAP_REG will be tuned at the factory.

Note 13: 0 dBm0 on COUT = -3.14 dB of max PCM value. COUT is CODEC output in test mode

Note 14: Trimming possibility is foreseen. At system production the bandgap reference voltage can be controlled within 2% accuracy and data can be stored in Flash. Either AVD or VREF can be trimmed within 2% accuracy. If AVD is trimmed VREF will be within 2% accuracy related to either AVD. Or vice versa VREF can be trimmed. For Vref trimming measure Δ (VREFp, VREFm) and update BANDGAP_REG[3:0].

Table 17: Microphone amplifier (Operating Condition)

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
Vmic_cm_level	MICp and MICn common mode voltage	MICp and MICn are set to GND with internal resistors (Rin_mic). If DC coupled the input voltage must be equal to this voltage.		(0.9 V/ 1.5)* VREFp		V

Table 18: Microphone supply voltages

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
Vref_unt	VREFp-VREFm untrimmed (Note 15)	I _{LOAD} = 0 mA BANDGAP_REG = 8 (Note 14)	1.41	1.5	1.59	V
Rout_vrefp	VREFp output resistance	Figure 8		1		Ω
Nvrefp_idle	Peak noise on VREFp-VREFm (Note 6)	CCITT weighted			-120	dBV
PSRRvrefp	Power supply rejection Vref output (Note 6)	See Figure 8, AVD to VREFp/m, f = 100 Hz to 4 kHz BANDGAP_REG[5:4] = 3	40			dB

Note 15: Vrefm is a clean ground input and is the 0 V reference.

Table 19: VREFp load circuit

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
Cload_vrefp	VREFp (parasitic) load capacitance				20	pF
Iout_vrefp	VREFp output current				1	mA

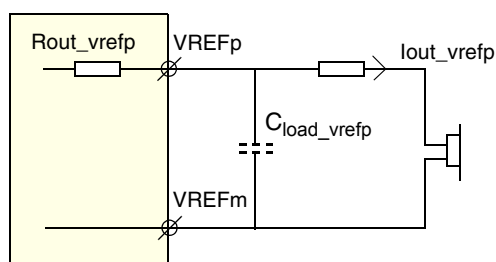


Figure 8: VREFp load circuit

Table 20: LSRp/LSRn outputs

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
Vlsr_0dB_unt	Untrimmed differential RMS output voltage between LSRp and LSRn in audio mode (0 dBm0 reference level)	0 dBm0 on CIN (Note 16), LSRATT[2:0] = 001, @ 1020 Hz Load circuit A (see Figure 9, Table 21) with RL1 = $\infty \Omega$, Cp1 or load circuit B (see Figure 10) with RL2, Cp2 and Cs2 Tolerance: • 13% when untrimmed (BANDGAP_REG=8) • 6% when trimmed (Note 14)	621	714	807	mV
Rout_lsr	Resistance of activated loudspeaker amplifier outputs LSRp and LSRn			1		Ω
Vlsr_dc	DC offset between LSRp and LSRn (Note 6)	LSRATT[2:0] = 3 RL1 = 28 Ω 3 sigma deviation limits	-20		20	mV

Note 16: 0 dBm0 on CIN = -3.14 dB of max PCM value.

Table 21: LSRp/LSRn load circuits

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
Cp1_RI1_inf	Load capacitance	see Figure 9, RL1 = ∞			30	pF
Cp1_RI1_1k	Load capacitance	see Figure 9, RL1 $\leq$ 1 k Ω			100	pF
RI1	Load resistance		28			Ω

Table 21: LSRp/LSRn load circuits

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
Cp2	Parallel load capacitance	see Figure 10			30	pF
Cs2	Serial load capacitance				30	μF
RI2	Load resistance		600			Ω

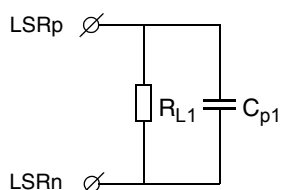


Figure 9: Load circuit A: Dynamic loudspeaker

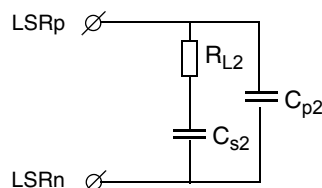


Figure 10: Load circuit B: Piezo loudspeaker

6.7 AUDIO PERFORMANCE

Table 22: Frequency response

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
Fco_low	Lower cutoff frequency (-3 dB)	Input voltage = -20 dBV rms Output voltage: -3 dBV rms		6		Hz
Fco_upr	Upper cutoff frequency (-3 dB)			11.3		kHz

Table 23: Distortion

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
THD	Total Harmonic Distortion	PA mode; PP: Vin = -30 dBV; measured on FP				
		f = 200 Hz, volume step 1		0.5		%
		f = 200 Hz, volume step 9		1.0		%
		f = 2 kHz, volume step 1		0.03		%
		f = 2 kHz, volume step 9		0.09		%

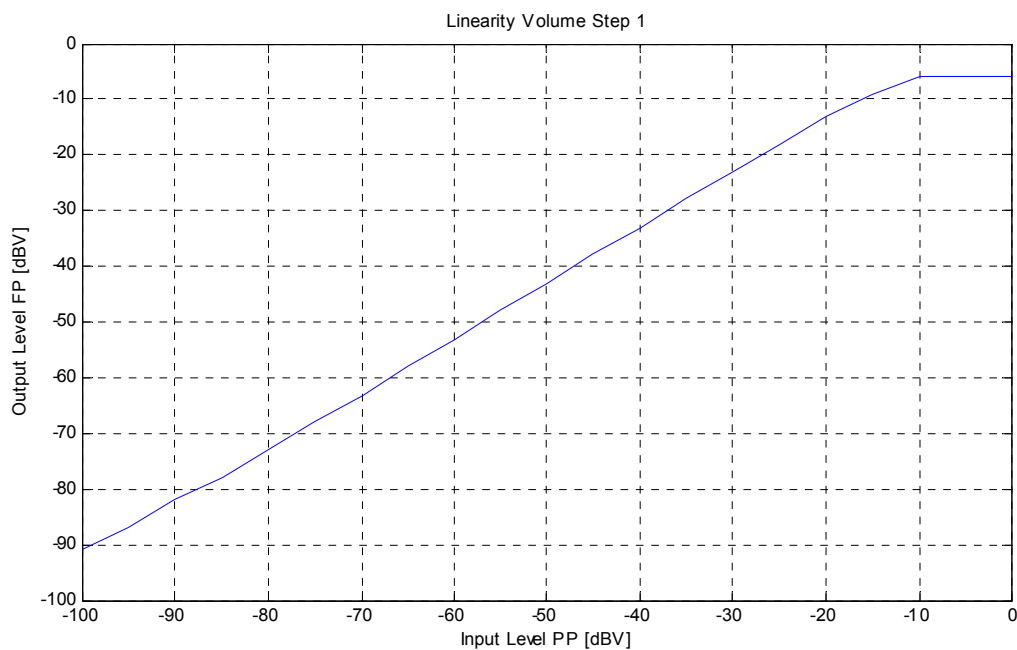


Figure 11: Linearity for a 1 kHz tone at volume step 1

6.8 BASEBAND PART

Table 24: Baseband specifications: UART

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
Fbit_uart	Serial interface bit rate	UART; Interface for external microprocessor or PC			115.2	kbit/s
Fbit_flash	Flash download bit rate	Via UART			115.2	kbit/s

6.9 RADIO (RF) PART

Standards compliancy: ETS 301 406 (former TBR6).

Table 25: Radio specifications

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
P_Rx	Receiver sensitivity	BER = 0.001; TA = 25 °C	-93	-92	-89	dBm
P_Rx_T	Receiver sensitivity, full temperature range	BER = 0.001; -40 °C ≤ TA ≤ +85 °C			-87	dBm
IPL	Intermodulation performance level (EN 301 406 section 4.5.7.6)	TA = 25 °C; Pw = -80 dBm; Δf = 2 channels	-35			dBm
NTP	Normal Transmitted Power (HPM: High Power Mode)	DECT	21	23	24.5	dBm
		DECT6.0 and Japan DECT			20	dBm
	Low Power mode			10		dBm
dPrfpa_T	RFPA power variation, full temperature range	-40 °C ≤ TA ≤ +85 °C		2.5	4	dB
Fbit	Bit rate	GFSK modulation		1.152		Mbit/s
BW_Tx	Transmitter bandwidth	DECT GFSK; NTP = 20 dB			1.728	MHz

Table 26: RFPA preferred settings for various power modes

Address (VES)	Register / Parameter	HPM/U (USA)	HPM (Europe)	HPM/J (Japan) (Note 17)
0x39	RF_PA_CTRL1_REG	0x09A0	0x0CF0	0x2CE0
0x3B	RF_TEST_MODE2_REG	0x0056	0x0062	0x0068
0x3D	RF_BBADC_CTRL_REG	0x0380	0x03A0	0x0398
0x05	RF_PLL_CTRL2_REG[MODINDEX]	0x25	0x25	0x23
0x23	Upper RSSI threshold	0x2C	N/A	0x28
0x24	Lower RSSI threshold	0x22	N/A	0x1E

Note 17: This power setting is only applicable for Full slot.

6.10 RF POWER SUPPLY

Table 27: Requirements for linear supply regulator

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
VBAT IN	Voltage at VBAT SW	Unloaded V _B Loaded V _B -V ₁ -V ₂ -V ₃	2.1	3	3.45	V
V ₁	Settling time	I = 50 mA			20	mV
V ₂	Receive period	I = 130 mA			100	mV
V ₂	Transmit period	I = 550 mA			200	mV
V ₃	Drop during transmit				25	mV

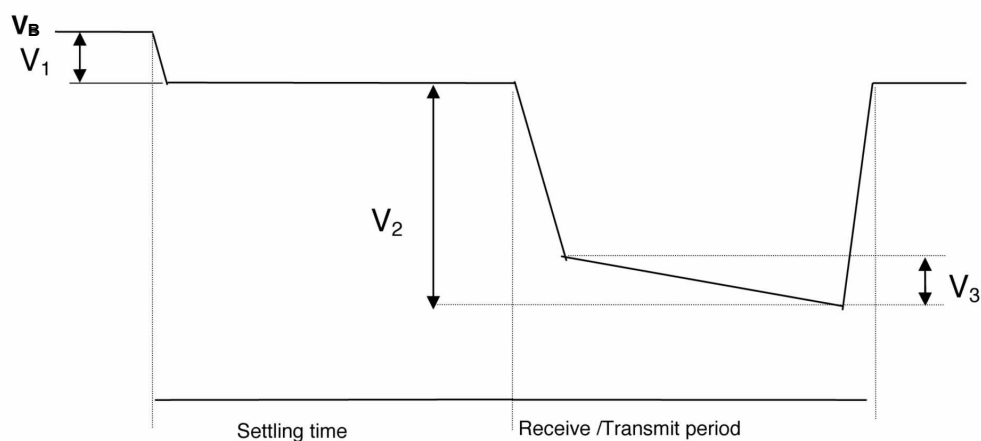


Figure 12: RF power supply

6.11 RF CHANNEL FREQUENCIES

Table 28: RF frequencies and channel numbers

Frequency (MHz)	Channel number		
	European DECT	Japan DECT	USA DECT 6.0
1787.616			
1789.344			
1791.072			
1881.792	9		
1883.520	8		
1885.248	7		
1886.976	6		
1888.704	5		
1890.432	4		
1892.160	3		
1893.888	2		
1895.616	1	4	
1897.344	0	-	
1899.072		-	
1900.800		-	
1902.528		0	
1921.536			4
1923.264			3
1924.992			2
1926.720			1
1928.448			0

7.0 Design guidelines

7.1 PCB DESIGN GUIDELINES

- Because of the presence of the digital radio frequency bursts with 100 Hz time division periods (TDD noise), supply ripple and RF radiation, special attention is needed for the power supply and ground PCB layout.
- Power supply considerations
Both high and low frequency bypassing of the supply line connections should be provided and placed as close as possible to the SC14WAMDECT SF. In order to get the best overall performance for both FP and PP applications, a number of considerations for the PCB has to be taken into account.
 - Make angle breaks on long supply lines to avoid resonances at DECT frequencies. Maximum 80 mm before an angle break is recommended.
 - Supply lines should be placed as far as possible away from sensitive audio circuits. If it is necessary to cross supply lines and audio lines, it should be done with right angles between supply and audio lines/circuits (microphone, ear-speaker, speakerphone, etc.)
- Ground plane considerations
In order to achieve the best audio performance and to avoid the influence of power supply noise, RF radiation, TDD noise and other noise sources, it is important that the audio circuits on both FP and PP applications boards are connected to the VREFm pin on the SC14WAMDECT SF with separate nets in the layout.
It is advised to provide the following audio circuits with separate ground nets connected to the VREFm pin:
 - Microphone(s)
 - Headset microphone and speaker
 - Speakerphone (signal grounds)

Depending on the layout it may also be necessary to bypass a number of the audio signals listed above to avoid humming, noise from RF radiation and TDD noise. It is also important to choose a microphone of appropriate quality with a high RF immunity (with built-in capacitor).

- ESD performance
Besides TDD noise, the ESD performance is important for the end application. In order to achieve a high ESD performance, supply lines should be placed with a large distance from charging terminals, display, headset connector and other electrical terminals with direct contact to the ESD source.
On a two-layer PCB application it is important to keep a simulated one layer ground. With a stable ground the ESD and TDD noise performance will always improve.
- Clearance around test patterns
Pins 81 to 88 are used for production test purposes.

In order to avoid any interference or disturbance the area around these signal pins must be kept clear of any signal and/or GND. The recommended clearance is at least 1 mm, as shown in Figure 13.

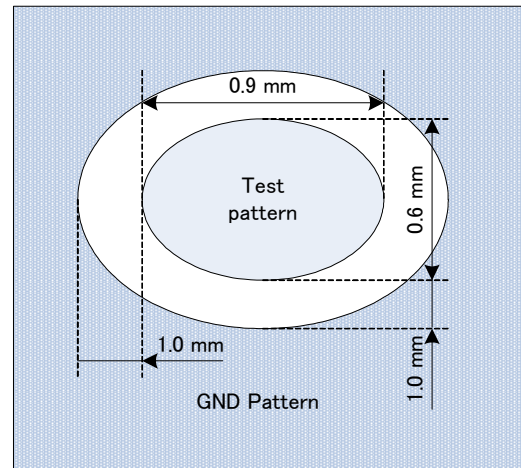


Figure 13: Clearance around test patterns

7.2 MODULE PLACEMENT ON THE MAIN BOARD

In order to ensure FCC compliance, proper coverage and to avoid detuning of the antennas, it is required to place the module on the main board free from other surrounding materials.

Keep a distance of at least 10 mm from the antenna elements to conducting objects and at least 5 mm to non-conducting objects.

Keep in mind that electrically shielding objects, even partly surrounding the antennas, will normally cause a significant degradation of the coverage.

Place the module at the edge of the main-board as shown in Figure 14.

When the module has to be placed away from the edge of the main board, avoid any conducting areas in front of the antennas and make a cut-out in the main board underneath the antennas as shown in the figure.

See Figure 18 and Figure 21 for the detailed package outline.

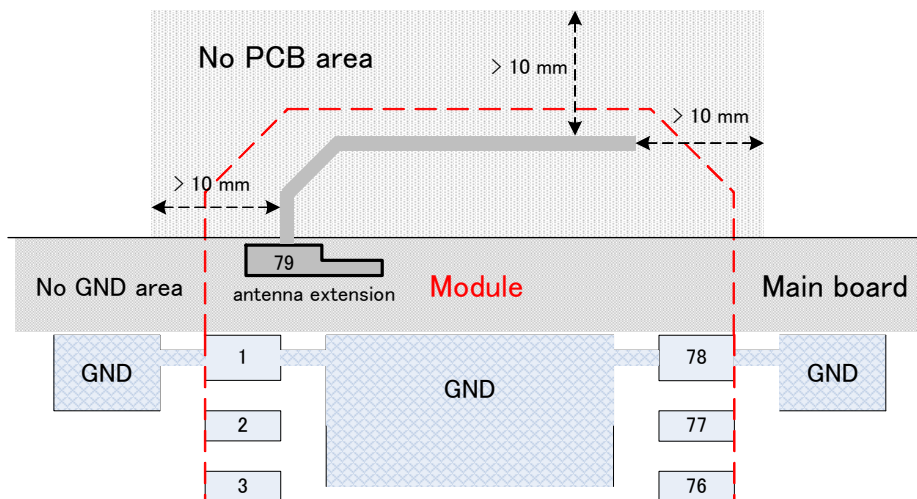


Figure 14: Module placement on the main board (top view)

7.3 PATTERN FOR PIN 79 ON THE MAIN BOARD

The copper pattern for pin 79 on the main board is very important because it is part of the internal antenna of the module. It is used to extend the internal antenna for optimum RF performance.

The PCB pattern shown in Figure 19 under “pads C” was used for pin 79 on the main board during module certification.

7.4 PRECAUTIONS REGARDING UNINTENDED COUPLING

The SC14WAMDECT SF includes an internal antenna, so at integration on the main board precautions shall be taken in order to avoid any kind of coupling from the main board to the RF part of the module.

If there is any doubt about this, a brief radio test should be performed.

8.0 Example application diagrams

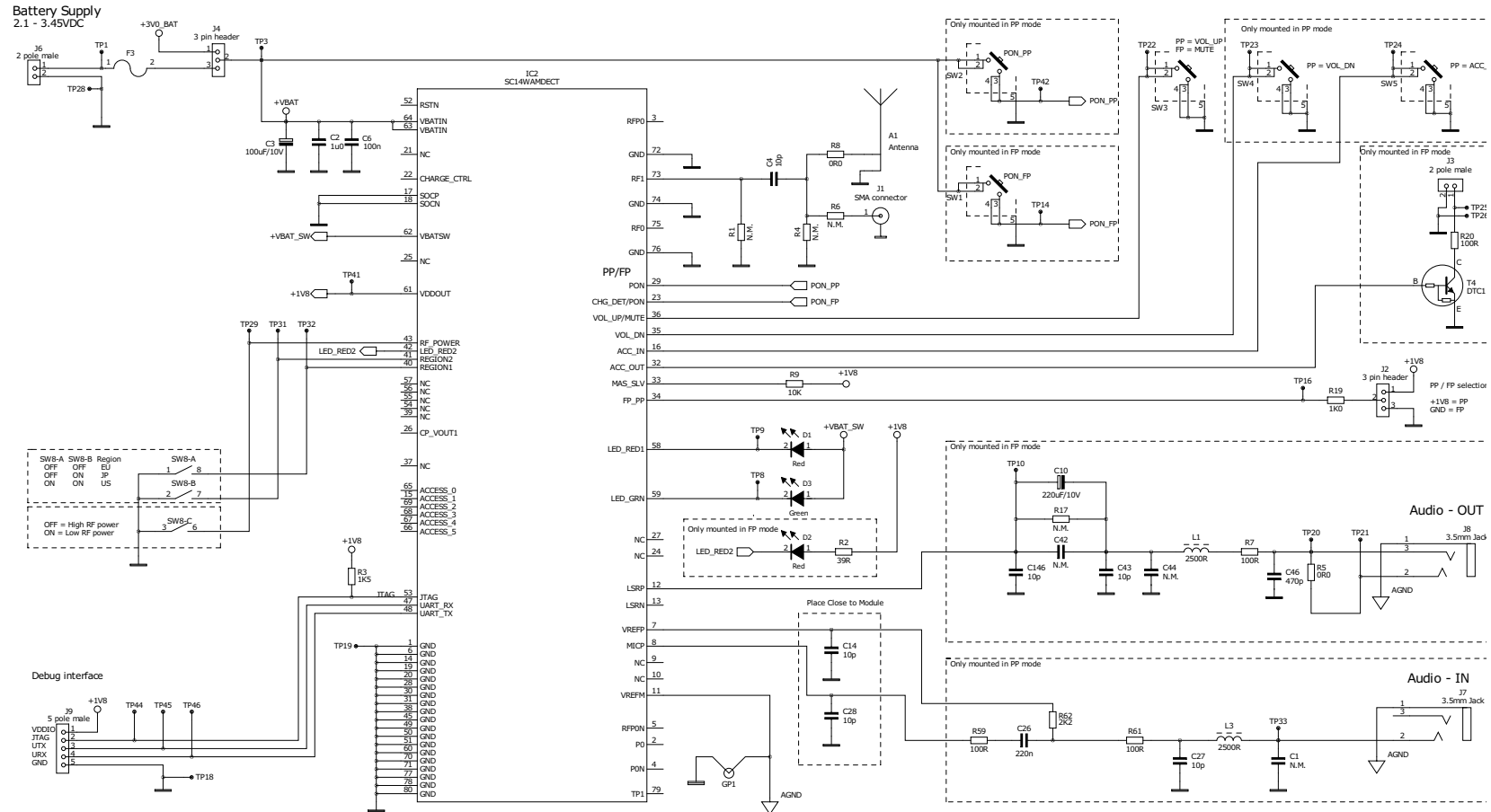


Figure 15: Example application diagram: Public Address mode

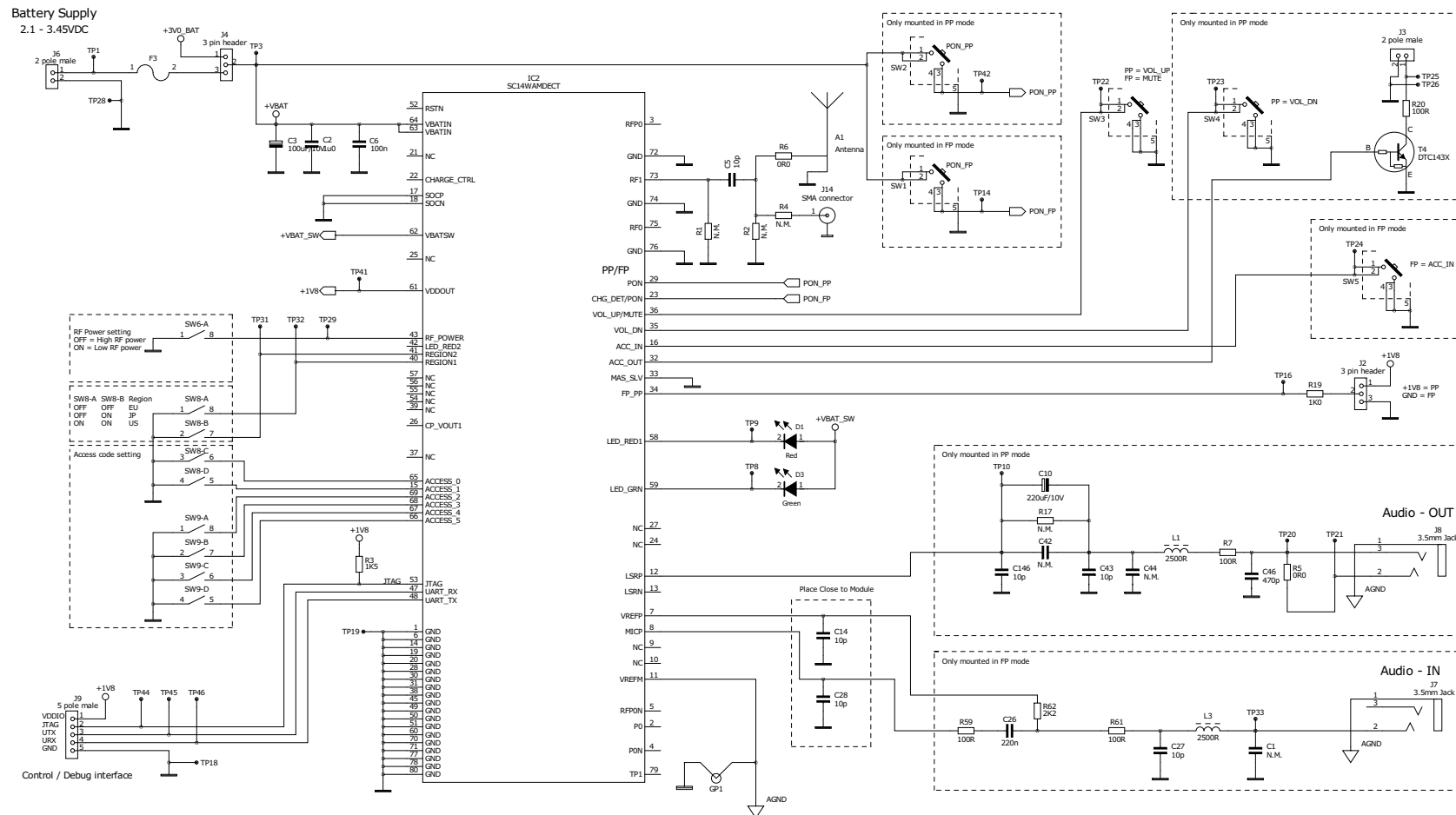


Figure 16 Example application diagram: Tour Guide mode

9.0 Notices to OEM

The end product has to be certified again when it has been programmed with other software than the Dialog standard software stack for portable part and/or uses one or two external antenna(s). (See [1] for more detailed information).

9.1 FCC REQUIREMENTS REGARDING THE END PRODUCT AND THE END USER

The end product that the module is integrated into must be marked as follows:

"Contains Transmitter Module FCC ID: Y82-SC14S / IC: 9576A-SC14S"

The literature provided to the end user must include the following wording:

FCC compliance statement

This device complies with Part 15 of the FCC Rules for **only portable part**.

Operation is subject to the following two conditions:

(1) this device may not cause harmful interference, and
(2) this device must accept any interference received, including interference that may cause undesired operation of the device.

Module transmetteur ID IC: 9576A-SC14S.

Son fonctionnement est soumis aux deux conditions suivantes: (1) cet appareil ne doit pas causer d'interférences nuisibles et (2) appareil doit accepter toute interférence reçue, y compris les interférences qui peuvent perturber le fonctionnement.

Changes or modifications to the equipment not expressly approved by the Party responsible for compliance could void the user's authority to operate the equipment.

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation.

This equipment generate, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation.

If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna

- Increase the separation between the equipment and receiver
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

Privacy of communications may not be ensured when using this phone.

9.2 INDUSTRY CANADA REQUIREMENTS REGARDING THE END PRODUCT AND THE END USER

The host device shall be properly labelled to identify the modules within the host device. The Industry Canada certification label of a module shall be clearly visible at all times when installed in the host device, otherwise the host device must be labelled to display the Industry Canada certification number of the module, preceded by the words "Contains transmitter module", or the word "Contains", or similar wording expressing the same meaning, as follows:

Contains transmitter module IC: 9576A-SC14S

L'appareil hôte doit être étiqueté comme il faut pour permettre l'identification des modules qui s'y trouvent. L'étiquette de certification d'Industrie Canada d'un module donné doit être posée sur l'appareil hôte à un endroit bien en vue en tout temps. En l'absence d'étiquette, l'appareil hôte doit porter une étiquette donnant le numéro de certification du module d'Industrie Canada, précédé des mots " Contient un module d'émission ", du mot " Contient " ou d'une formulation similaire exprimant le même sens, comme suit :

Contient le module d'émission IC: 9576A-SC14S

This device complies with Industry Canada licence-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes : (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

CAN ICES-3 (B)/NMB-3(B)

9.3 END APPLICATION APPROVAL

The module is intended to be used in an end application. Type approval concerning the end product, except for the module, should of course be done. Please contact a test house in order to clarify what is needed.

9.4 SAFETY REQUIREMENTS

This section provides of an overview of the safety requirements that must be adhered to when working with the SC14WAMDECT SF.

- The specific external power supply for the SC14WAMDECT SF has to fulfil the requirements according to clause 2.5 (Limited power source) of this standard EN 60950-1:2006.
- Interconnection circuits shall be selected to provide continued conformance to the requirements of clause 2.2 for SELV (Safety Extra Low Voltage) circuits according to EN 60950-1:2006 after making connections.
- Interface type: not subjected to overvoltages (i.e. does not leave the building).
- Requirements additional to those specified in this standard may be necessary for:
 - Equipment intended for operation in special environments (for example, extremes of temperature, excessive dust, moisture or vibration, flammable gases and corrosive or explosive atmospheres).
 - Equipment intended to be used in vehicles, on board ships or aircraft, in tropical countries or at altitudes greater than 2000 m.
 - Equipment intended for use where ingress of water is possible.
- Installation by qualified personnel only!
- The product is a component intended for installation and use in complete equipment. The final acceptance of the component is dependent upon its installation and use in complete equipment.

10.0 Package information

10.1 SOLDERING PROFILE

The SC14WAMDECT SF should be soldered using a lead-free reflow soldering profile as shown below. Adjustments to the profile may be necessary depending on process requirements.

Recommended solder paste for lead-free soldering:

Sn 96.5 % - Ag 3.0 % - Cu 0.5 %.

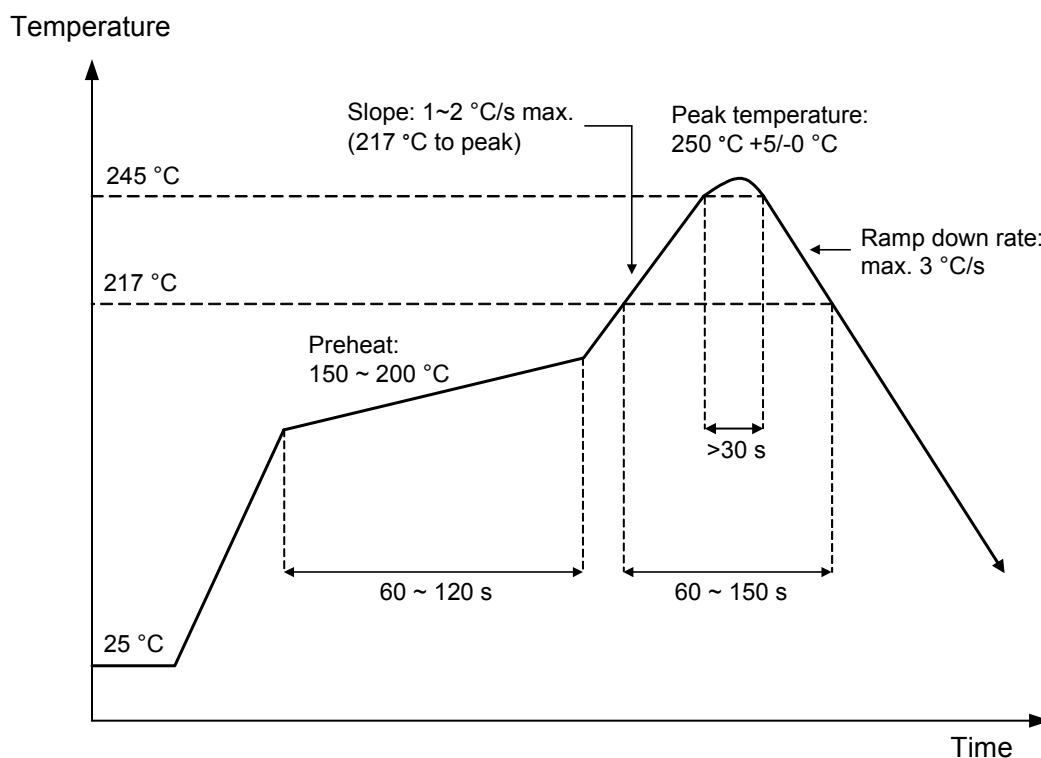


Figure 17: Reflow profile (lead-free)

10.2 MOISTURE SENSITIVITY LEVEL (MSL)

The MSL is an indicator for the maximum allowable time period (floor life time) in which a moisture sensitive plastic device, once removed from the dry bag, can be exposed to an environment with a maximum temperature of 30 °C and a maximum relative humidity of 60 % RH. before the solder reflow process.

The SC14WAMDECT SF is qualified to MSL 3.

MSL Level	Floor Life Time
MSL 4	72 hours
MSL 3	168 hours
MSL 2A	4 weeks
MSL 2	1 year
MSL 1	Unlimited at 30 °C/85 % RH

10.3 COPPER PAD, SOLDER OPENING AND STENCIL

For the stencil a thickness of 0.130 mm is recommended. Recommended copper pad, solder mask opening and stencil are shown below.

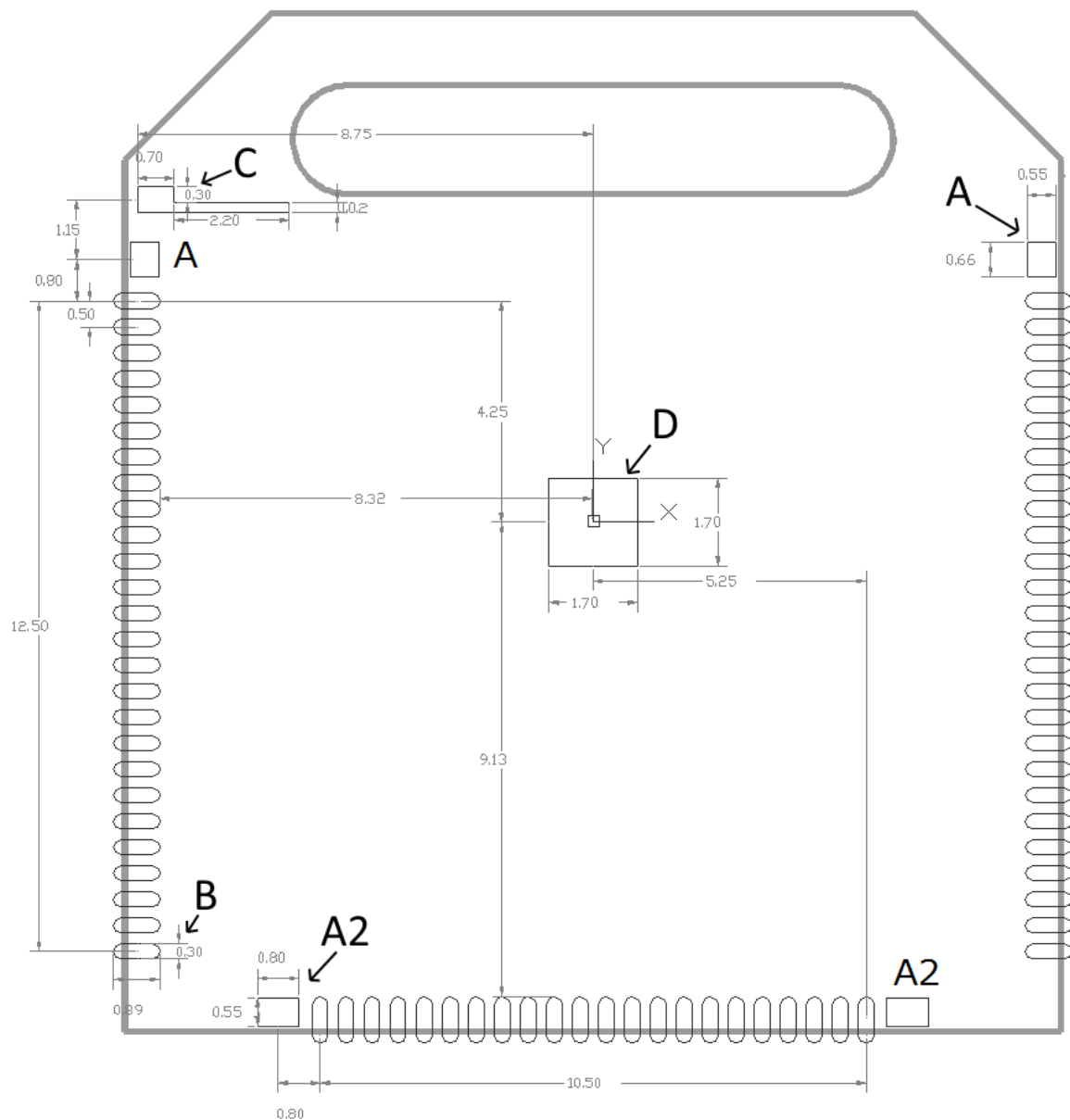


Figure 18: Pad types and dimensions

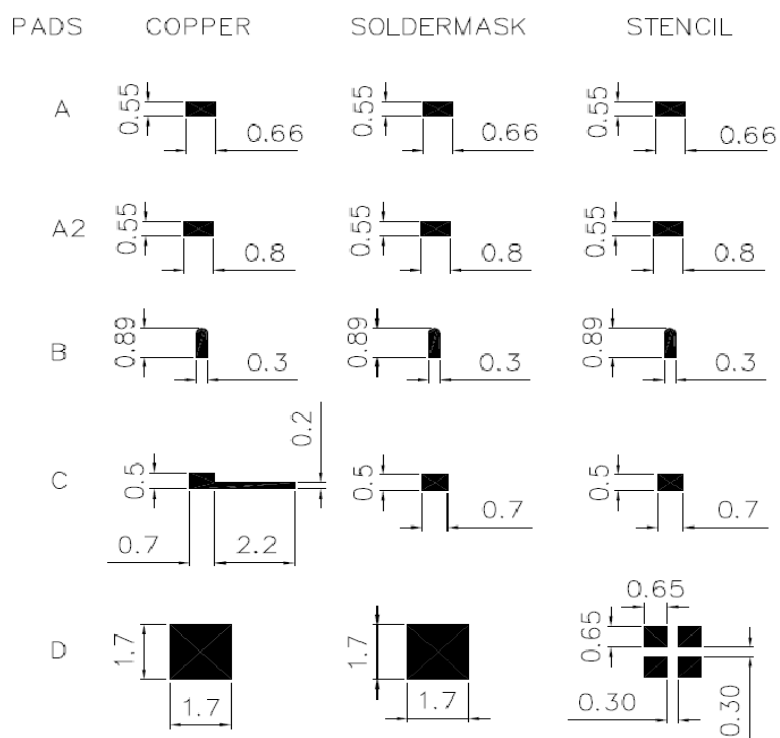


Figure 19: Copper pad, solder mask opening and stencil

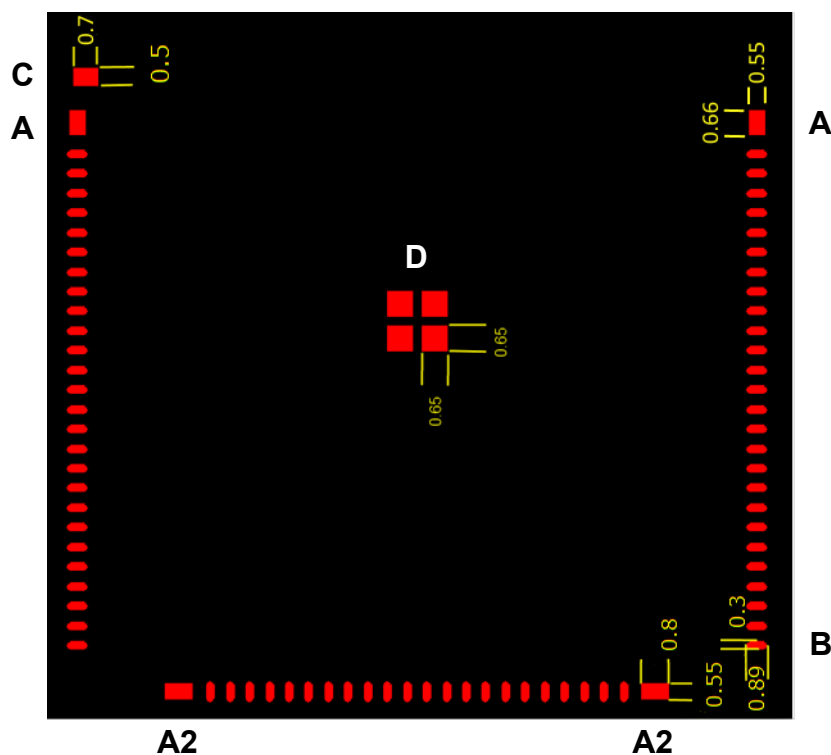


Figure 20: Solder stencil

10.4 MECHANICAL DIMENSIONS

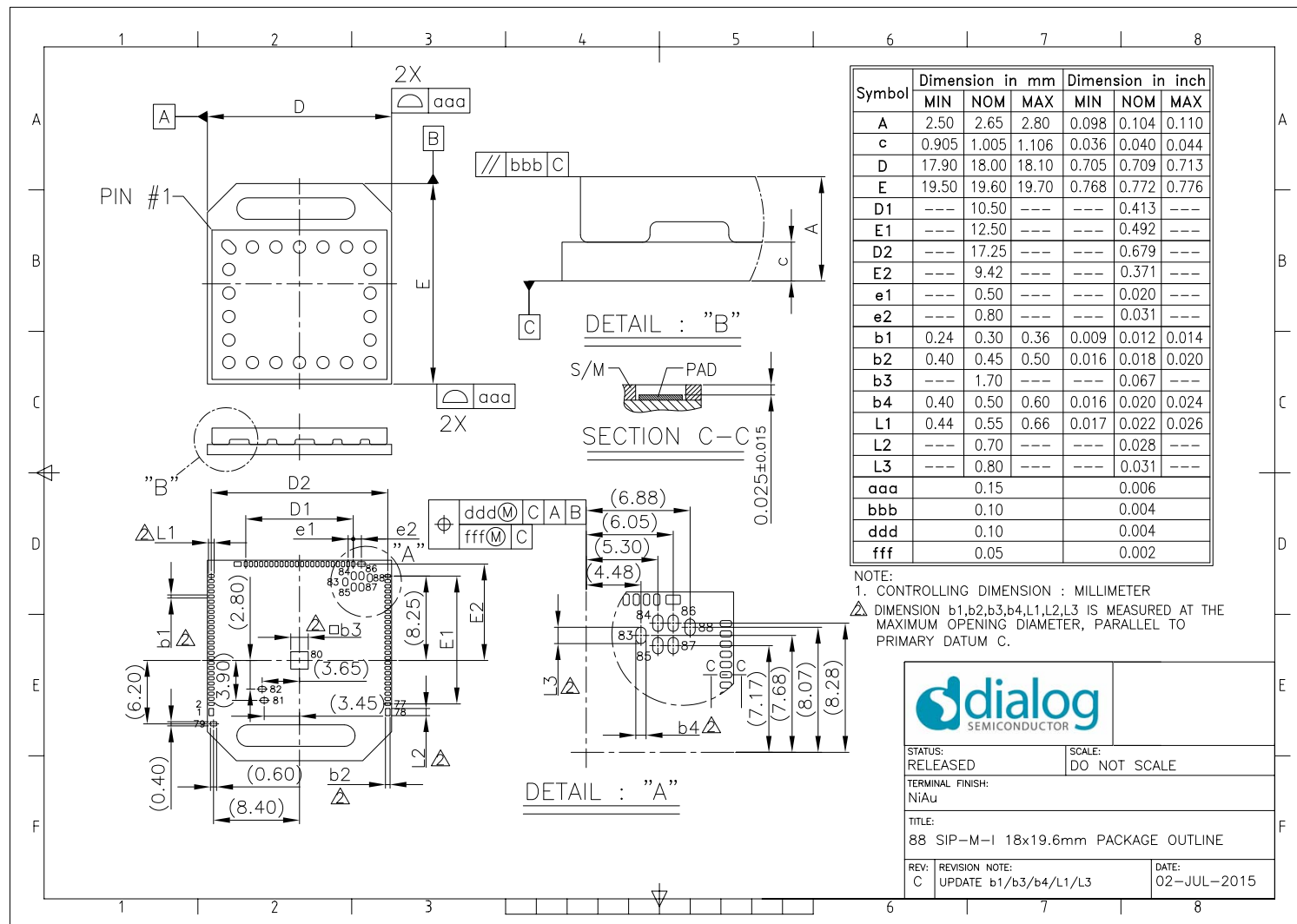


Figure 21: Package outline drawing

11.0 Revision history

19-Nov-2013 v1.0:

- Initial version

27-Nov-2013 v1.1:

- Antenna diversity description updated in sections 4.4 and 5.6.2.

14-Jan-2014 v1.11:

- Updated connection diagram, Pin description, Speaker configuration (section 3.3).
- Added section 6.7 (Audio performance).

14-Jan-2014 v1.12:

- Corrected Pin description.
- Updated Table 5 and Battery low/empty voltage in section 5.1.
- Updated section 10.3.

11-Feb-2014 v1.13:

- Corrected section 10.3.

18-Mar-2014 v1.20:

- Corrected system diagram.
- Corrected pin description for pin #26.
- Description for pin RED_LED2 updated.
- Added "Example application diagrams" on page 27.

27-Mar-2014 v1.21:

- Feature list updated.

29-Aug-2014 v1.22:

- Text changed for J-DECT certify as "Pre-certified".
- Explanation for the Pin description changed.
- Volume control section updated.
- Low battery indication added in section 5.5.
- Added explanation for RF1 in section 5.6.
- KDECT explanation added.
- PTT changed to AIPP and AOFP.
- Accessory Input (AIPP) and output (AOFP) section added (section 5.1.5).
- Wire registration added to section 3.4 and section 4.5.
- Usage Guidelines (section 5.0) updated.

10-Oct-2014 v1.23:

- Updated latency value for TG mode.
- Added low power mode.

23-Jul-2015 v3.0 (Final):

- Product status: Production.
- Korean DECT mode removed: not supported.
- Section 1.0:
 - Connection diagram updated (Figure 1).
 - PP and FP removed from pin names.
 - Unused pins changed to NC.
- Pins AIPP and AOFP renamed to ACC_IN and ACC_OUT.
- Pin 11 (GND) renamed to VREFm.
- Added pins ACCESS_0 to ACCESS_5 (pins 65, 15, 69 to 66).
- Removed battery management section (charging is not supported).
- Supply currents moved from section 6.8 to new section 6.4.
- Updated supply currents (Table 12 and Table 13).
- Example application diagrams added for PA and TG mode.
- Section 10.0:
 - Reflow soldering profile updated (Figure 17).
 - Soldering stencil thickness changed to 0.130 mm.
 - Package outline drawing updated (Figure 21).
- Back page:
 - Status definition table updated.
 - Contact information updated.
- Template updated to latest version.

Status definitions

Version	Datasheet status	Product status	Definition
1.<n>	Target	Development	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
2.<n>	Preliminary	Qualification	This datasheet contains the specifications and preliminary characterisation data for products in pre-production. Specifications may be changed at any time without notice in order to improve the design.
3.<n>	Final	Production	This datasheet contains the final specifications for products in volume production. The specifications may be changed at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via Customer Product Notifications.
4.<n>	Obsolete	Archived	This datasheet contains the specifications for discontinued products. The information is provided for reference only.

Disclaimer

Information in this document is believed to be accurate and reliable. However, Dialog Semiconductor does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information. Dialog Semiconductor furthermore takes no responsibility whatsoever for the content in this document if provided by any information source outside of Dialog Semiconductor.

Dialog Semiconductor reserves the right to change without notice the information published in this document, including without limitation the specification and design of the related semiconductor products, software and applications.

Applications, software, and semiconductor products described in this document are for illustrative purposes only. Dialog Semiconductor makes no representation or warranty that such applications, software and semiconductor products will be suitable for the specified use without further testing or modification. Unless otherwise agreed in writing, such testing or modification is the sole responsibility of the customer and Dialog Semiconductor excludes all liability in this respect.

Customer notes that nothing in this document may be construed as a license for customer to use the Dialog Semiconductor products, software and applications referred to in this document. Such license must be separately sought by customer with Dialog Semiconductor.

All use of Dialog Semiconductor products, software and applications referred to in this document are subject to Dialog Semiconductor's Standard Terms and Conditions of Sale, unless otherwise stated.

© Dialog Semiconductor. All rights reserved.

RoHS compliance

Dialog Semiconductor complies to European Directive 2001/95/EC and from 2 January 2013 onwards to European Directive 2011/65/EU concerning Restriction of Hazardous Substances (RoHS/RoHS2). Dialog Semiconductor's statement on RoHS can be found on the customer portal <https://support.diasemi.com/>. RoHS certificates from our suppliers are available on request.

Contacting Dialog Semiconductor

United Kingdom (Headquarters)

Dialog Semiconductor (UK) LTD
Phone: +44 1793 757700

Germany

Dialog Semiconductor GmbH
Phone: +49 7021 805-0

The Netherlands

Dialog Semiconductor B.V.
Phone: +31 73 640 8822

Email:

enquiry@diasemi.com

North America

Dialog Semiconductor Inc.
Phone: +1 408 845 8500

Japan

Dialog Semiconductor K. K.
Phone: +81 3 5425 4567

Taiwan

Dialog Semiconductor Taiwan
Phone: +886 281 786 222

Web site:

www.dialog-semiconductor.com

Singapore

Dialog Semiconductor Singapore
Phone: +65 64 8499 29

Hong Kong

Dialog Semiconductor Hong Kong
Phone: +852 3769 5200

Korea

Dialog Semiconductor Korea
Phone: +82 2 3469 8200

China (Shenzhen)

Dialog Semiconductor China
Phone: +86 755 2981 3669

China (Shanghai)

Dialog Semiconductor China
Phone: +86 21 5424 9058